



APPENDIX D

(VERSION OF CLAIMS AS AMENDED HEREIN
WITH MARKINGS TO SHOW CHANGES MADE)

(Serial No. 09/942,245)

VERSION OF CLAIMS WITH MARKINGS TO SHOW CHANGES MADE

10. (Amended) A semiconductor assembly comprising:
a semiconductor device having an active surface;
a substrate having an upper surface;
a wetting agent located on a portion of one of said active surface of said semiconductor
[die]device and said upper surface of said substrate; and
an underfill material located between said substrate and said semiconductor device.